

# United States Patent [19]

Ohta et al.

[11] Patent Number: 4,985,471

[45] Date of Patent: Jan. 15, 1991

[54] RADIATION CURABLE PRESSURE  
SENSITIVE ADHESIVE COMPOSITION

[75] Inventors: Tomohisa Ohta, Tochigi; Hiroyuki  
Hagiwara, Shimodate; Hisashige  
Kanbara, Shimodate; Akihiko  
Dobashi, Shimodate; Yasuyuki Seki,  
Hitachi, all of Japan

[73] Assignee: Hitachi Chemical Company Ltd.,  
Tokyo, Japan

[21] Appl. No.: 183,633

[22] Filed: Apr. 19, 1988

[30] Foreign Application Priority Data

Apr. 20, 1987 [JP] Japan ..... 62-97199

[51] Int. Cl.<sup>5</sup> ..... C08F 2/46

[52] U.S. Cl. .... 522/27; 522/182;  
526/220; 526/222; 526/348.2

[58] Field of Search ..... 522/27

[56] References Cited

## U.S. PATENT DOCUMENTS

3,843,502 10/1974 Pearson et al. .... 522/27  
4,144,154 3/1979 Zapp et al. .... 522/27

4,275,142 6/1981 Hosaka et al. .... 522/65

Primary Examiner—Marion E. McCamish

Assistant Examiner—Susan Berman

Attorney, Agent, or Firm—Antonelli, Terry, Stout &  
Kraus

## [57] ABSTRACT

A radiation curable pressure sensitive adhesive composition comprising:

(A) 100 parts by weight of a hydrogenated polybutadiene liquid oligomer which has one or more ethylenically unsaturated terminal radicals in its molecule and in which 70% or more of intramolecular carbon-carbon double bonds has been hydrogenated;

(B) from 0.2 to 20 parts by weight of a chain transfer agent; and

(C) from 0.001 to 1.0 parts by weight of a thermal polymerization inhibitor selected from metal complexes of N-nitrosophenylhydroxylamine;

has an excellent storage stability and curing property and can provide pressure sensitive adhesive tapes which have excellent heat resistance and weatherability and are suitably used as surface protecting films.

8 Claims, No Drawings